




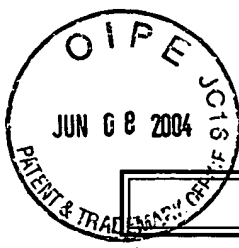
IPW

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Electronic Patent Application Submission
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EFS ID: 62260
Application ID: 10774194 
Title of Invention: METHOD AND APPARATUS FOR
INFILM DEFECT REDUCTION FOR
ELECTROCHEMICAL COPPER
DEPOSITION
First Named Inventor: YI-CHIAU HUANG
Domestic/Foreign Application: Domestic Application
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**TRANSMITTAL**

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	METHOD AND APPARATUS FOR INFILM DEFECT REDUCTION FOR ELECTROCHEMICAL COPPER DEPOSITION						
Application Number: 10/774194 Date: 2004-02-05 First Named Applicant: YI-CHIAU Confirmation Number: 6951 Attorney Docket Number: AMAT8461							
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Submitted by:	Elec. Sign.	Sign. Capacity					
Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney					
Documents being submitted us-ids	Files AMAT8461NAN-usidst.xml us-ids.dtd us-ids.xsl						
Comments NO FEES DUE - FILED BEFORE 1ST OA							



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

METHOD AND APPARATUS FOR INFILM DEFECT
REDUCTION FOR ELECTROCHEMICAL COPPER
DEPOSITION

Application Number: 10/774194
Confirmation Number: 6951
First Named Applicant: YI-CHIAU HUANG
Attorney Docket Number: AMAT8461
Art Unit: 2812
Search string: (4557785 or 5022419 or 5095027 or 5154199
or 5221360 or 5409310 or 6039059 or 6062239
or 6167893 or 6199298 or 6200876 or 6217667
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or 6350319 or 6357142 or 6401732 or 6413436
or 6446643 or 6446644 or 6463938 or 6537416
or 6547660 or 6550484 or 6558053 or 6558478
or 6569696 or 6615854 or 6684891 or 6722557
or 20020026729).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	5022419	1991-06-11	THOMPSON, ET AL.			
	3	5095027	1992-03-10	GOLDBERG, ET AL.			
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US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020026729	2002-03-07	BERGMAN, ET AL.			

Remarks

Note: Remarks are not for responding to an office action.

NO FEES DUE - FILED BEFORE 1ST OA



Signature

Examiner Name	Date